

METHOD AND APPARATUS FOR REDUCED PIN COUNT PACKAGE CONNECTION VERIFICATION

Abstract of the Disclosure

A method and apparatus for testing the chip-to-package connectivity of a common I/O of a semiconductor chip is disclosed which uses reduced pin count testing methods. The method includes driving a test signal transition onto a control pad of a semiconductor chip with a weak driver and comparing the transition rise time with a threshold value. For an I/O with a faulty chip-to-package connection, the rise time is much faster than for an I/O with a completed chip-to-package connection. Additional impedances may also be added to the tester fixturing to increase the sensitivity of the test equipment to the capacitance of the I/O connections.

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